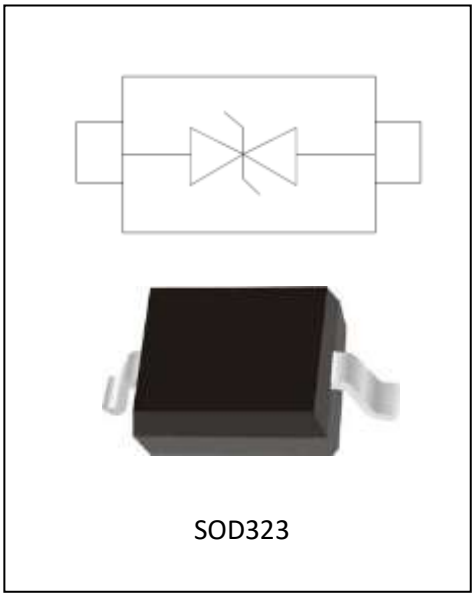
Features

- 150 Watts peak pulse power (tp = 8/20μs)
- Transient protection for high speed data lines to
  IEC 61000-4-2 (ESD) ±15kV (air), ±8kV (contact)
  IEC 61000-4-4 (EFT) 40A (5/50ns)
- Protects One Power or I/O Port
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology



SOD323

Applications

- Cell Phone Handsets and Accessories
- Microprocessor based equipment
- Portable Instrumentation
- Personal Digital Assistant (PDA)

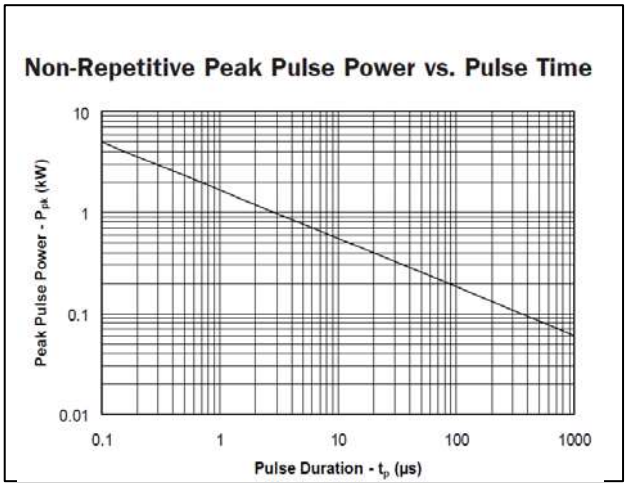
Maximum Rating @ Ta=25℃ unless otherwise specified

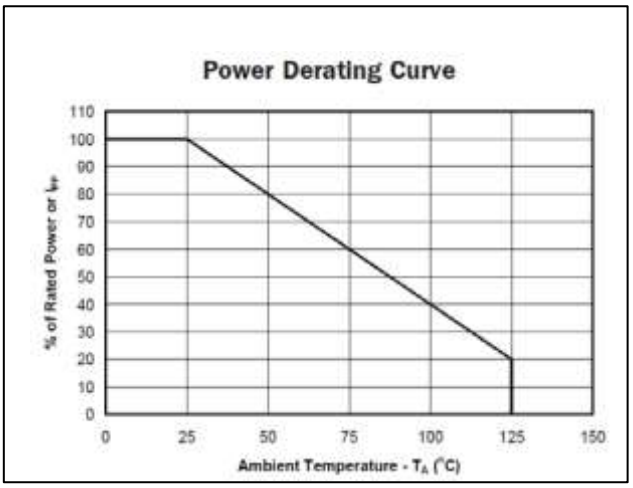
Symbol	Parameter	Ratings	Units
P_{PK}	Peak Pulse Power (tp = 8/20μs)	150	Watts
T_L	Lead Soldering Temperature	260(10sec.)	℃
T_J	Operating Temperature	-55 to +125	℃
T_{STG}	Storage Temperature	-55 to +150	℃

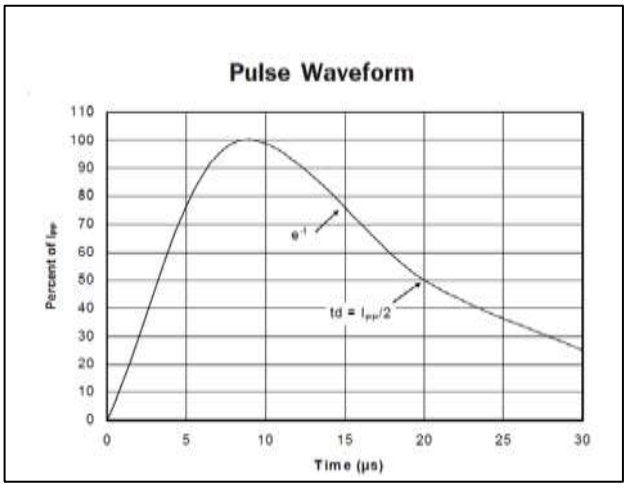
Electrical Characteristics@ Ta=25℃ unless otherwise

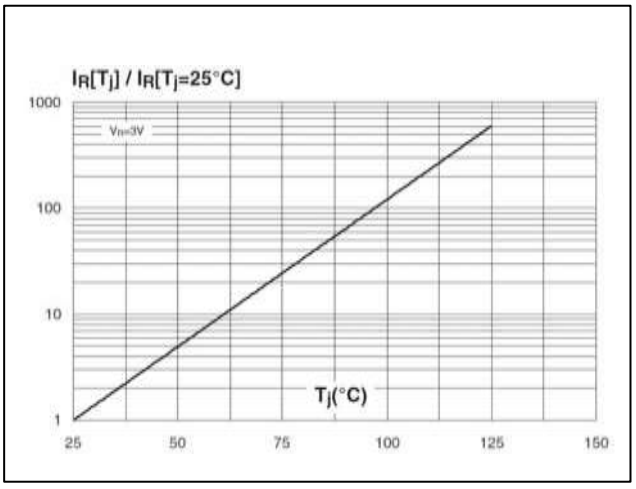
Parameter	Marking	V_{RWM} @I_R		V_{BR}@ImA	V_C@1A	V_C@I_{PP}		C_J
		V	μA	V	V	V	A	pF
			MAX	MIN	MAX	MAX		MAX
SD03C		3.3	1	4.6	9.8	14	12	120
SD05C		5	1	5.8	11.8	15	10	100
SD08C		8	1	8.2	14.5	19	8	80
SD12C		12	1	13.3	19	25	6	70
SD15C		15	1	16.5	24	33	5	50
SD24C		24	1	26.1	44	54	3	30

Typical Characteristics@ Ta=25℃ unless otherwise specified



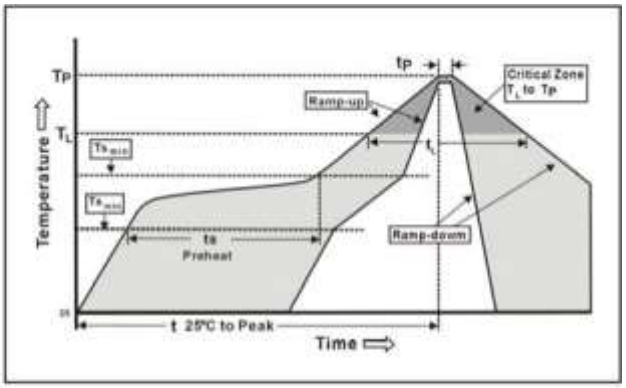






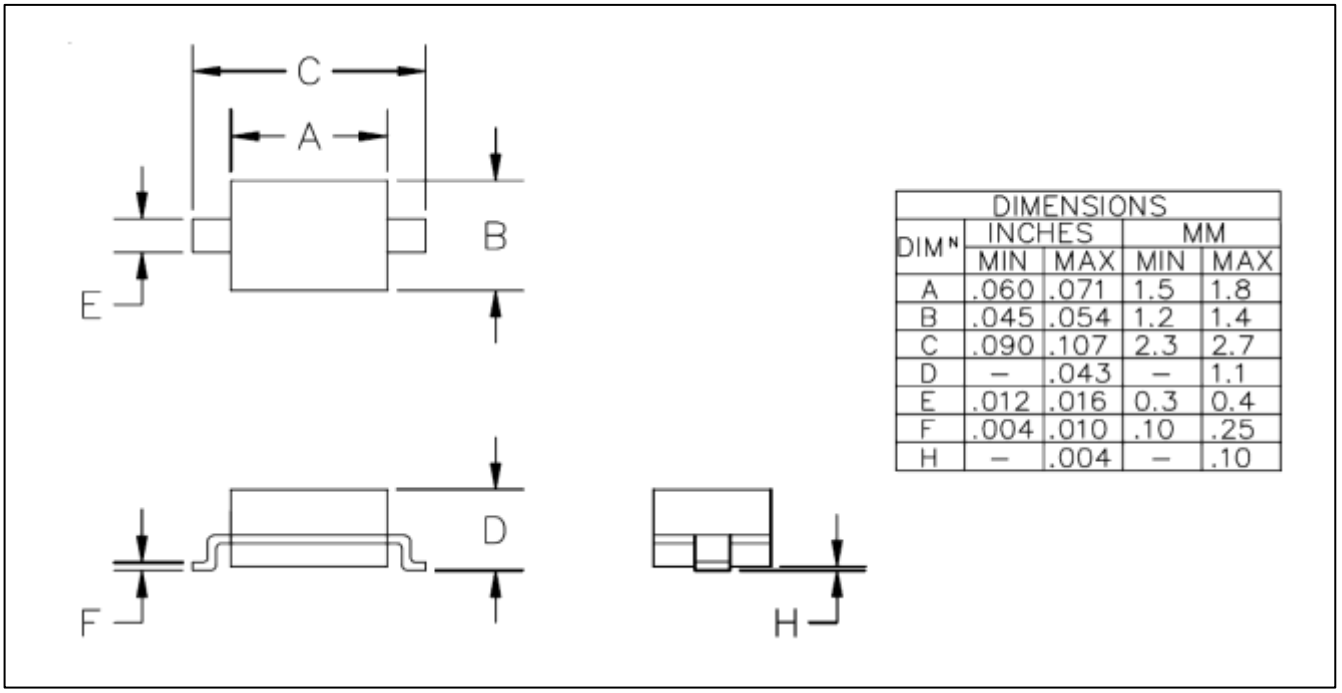
Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	-Temperature Min ($T_{s(Min)}$)	150°C
	-Temperature Max ($T_{s(Max)}$)	200°C
	-Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus) Temp (T_L) to peak		3°C/second Max
$T_{S(Max)}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	-Temperature (T_L) (Liquidus)	217°C
	-Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-dowm Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C



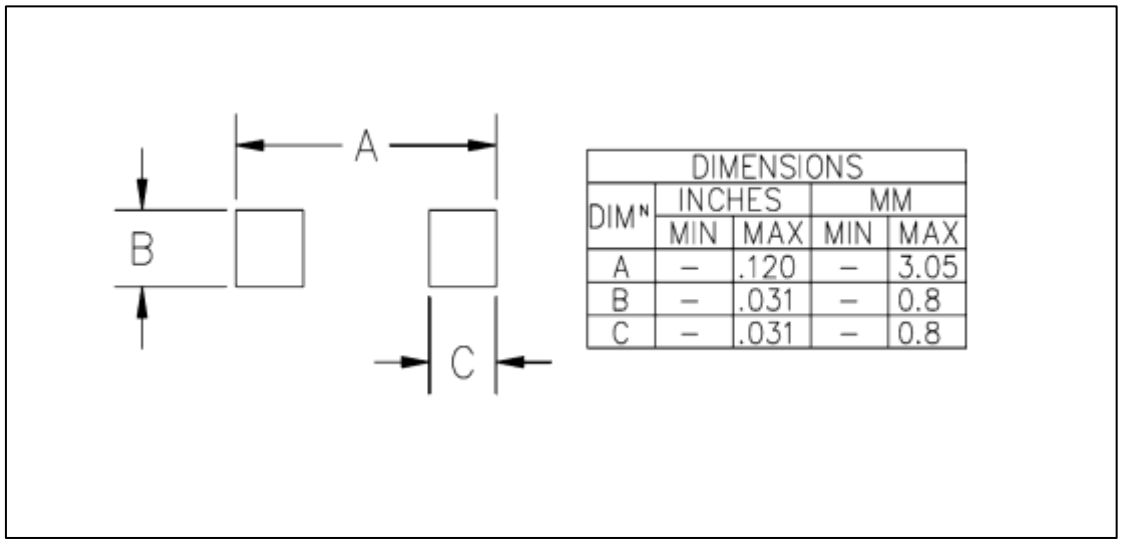
Package Outline

Plastic surface mounted package SOD323



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	.060	.071	1.5	1.8
B	.045	.054	1.2	1.4
C	.090	.107	2.3	2.7
D	–	.043	–	1.1
E	.012	.016	0.3	0.4
F	.004	.010	.10	.25
H	–	.004	–	.10

Soldering Footprint



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	–	.120	–	3.05
B	–	.031	–	0.8
C	–	.031	–	0.8

Package And Marking Information

Device	Package	Shipping	Reel Size
SDxxC	SOD323	3000/Reel	7 inch